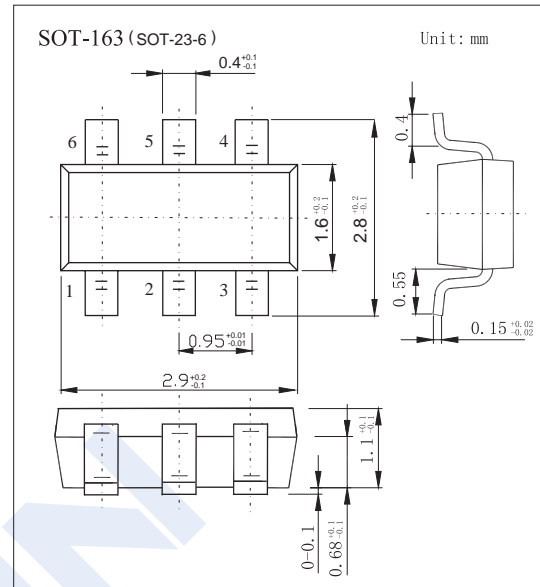
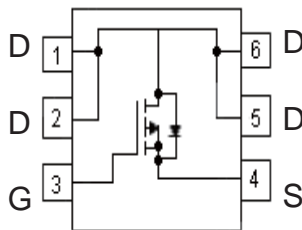


## P-Channel MOSFET

### 2KJ6068

#### ■ Features

- $V_{DS} (V) = -60V$
- $I_D = -6.5 A$
- $R_{DS(ON)} = 50m\Omega @ V_{GS} = -10V$
- $R_{DS(ON)} = 60m\Omega @ V_{GS} = -4.5V$



#### ■ Absolute Maximum Ratings ( $T_A = 25^\circ C$ , unless otherwise noted)

Parameter	Symbol	Rating	Unit	
Drain-Source Voltage	$V_{DS}$	-60	V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$		
Continuous Drain Current	$I_D$	$T_C = 25^\circ C$	A	
		$T_C = 70^\circ C$		
		$T_A = 25^\circ C$		
		$T_A = 70^\circ C$		
Pulsed Drain Current	$I_{DM}$	-20		
Continuous Drain Current	$I_S$	$T_C = 25^\circ C$	-3.5	
		$T_A = 25^\circ C$		-1.7 <sup>a,b</sup>
Avalanche Current	$I_{AS}$	-15		
Single Pulse Avalanche Energy	$E_{AS}$	11.25	mJ	
Maximum Power Dissipation	$P_D$	$T_C = 25^\circ C$	W	
		$T_C = 70^\circ C$		
		$T_A = 25^\circ C$		
		$T_A = 70^\circ C$		
Thermal Resistance, Junction- to-Ambient <sup>a,c</sup>	$t \leq 10 s$	$R_{\theta JA}$	62.5	$^\circ C/W$
Thermal Resistance, Junction- to-Foot	Steady State	$R_{\theta JF}$	30	
Junction Temperature	$T_J$	150	$^\circ C$	
Junction Storage Temperature Range	$T_{stg}$	-55 to 150		

Notes: 1. Surface mounted on 1" x 1" FR4 board.

2.  $t = 10 s$ .

3. Maximum under steady state conditions is 110  $^\circ C/W$ .

4. Based on  $T_C = 25^\circ C$ .

## P-Channel MOSFET

### 2KJ6068

#### ■ Electrical Characteristics (T<sub>J</sub> = 25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> =-250μA, V <sub>GS</sub> =0V	-60			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-60V, V <sub>GS</sub> =0V			-1	μA
		V <sub>DS</sub> =-60V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C			-5	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ -10 V, V <sub>GS</sub> = -10 V	-30			A
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.5		-2	V
Static Drain-Source On-Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-3.5A		50		mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2.8A		60		
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> =-30 V, I <sub>D</sub> =-3.5 A		11		S
<b>Dynamic<sup>b</sup></b>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =-30V, f=1MHz		832		pF
Output Capacitance	C <sub>oss</sub>			88		
Reverse Transfer Capacitance	C <sub>rss</sub>			63		
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-30 V, V <sub>GS</sub> =-10V, I <sub>D</sub> =-3.5 A		20	30	nC
				10.1	15.2	
Gate Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =-30 V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3.5 A		3.3		
Gate Drain Charge	Q <sub>gd</sub>			3.9		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	1.8	9	18	Ω
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-30 V, R <sub>L</sub> =10.7 Ω, I <sub>D</sub> =-2.8 A, V <sub>GEN</sub> =-10 V, R <sub>g</sub> =1Ω		8	16	ns
Turn-On Rise Time	t <sub>r</sub>			6	12	
Turn-Off Delay Time	t <sub>d(off)</sub>			35	53	
Turn-Off Fall Time	t <sub>f</sub>			16	24	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-30 V, R <sub>L</sub> =10.7 Ω, I <sub>D</sub> =-2.8 A, V <sub>GEN</sub> =-4.5V, R <sub>g</sub> =1 Ω		40	60	ns
Turn-On Rise Time	t <sub>r</sub>			28	42	
Turn-Off Delay Time	t <sub>d(off)</sub>			31	47	
Turn-Off Fall Time	t <sub>f</sub>			15	23	
<b>Drain-Source Body Diode Characteristics</b>						
Maximum Body-Diode Continuous Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			-3.5	A
Maximum Body-Diode Pulsed Current	I <sub>SM</sub>				-20	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = -2.8A, V <sub>GS</sub> =0V		-0.85	-1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = -2.8 A, di/dt = 100 A/μs, T <sub>J</sub> = 25 °C		32	48	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			45	68	nC
Reverse Recovery Fall Time	t <sub>a</sub>			24		ns
Reverse Recovery Rise Time	t <sub>b</sub>			8		

Notes a. Pulse Test: Pulse width ≤ 300μs, Duty cycle ≤ 2%

b. Guaranteed by design, not subject to production testing.

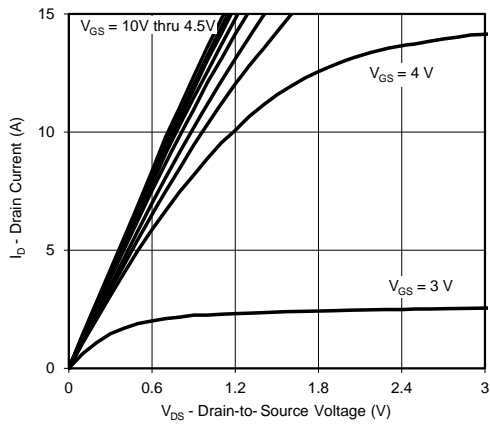
#### ■ Marking

Marking	6068 ‡
---------	--------

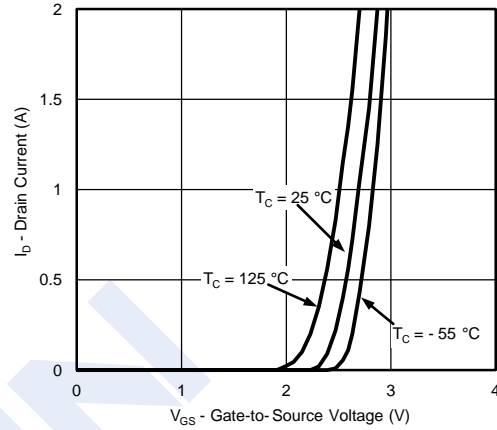
# P-Channel MOSFET

## 2KJ6068

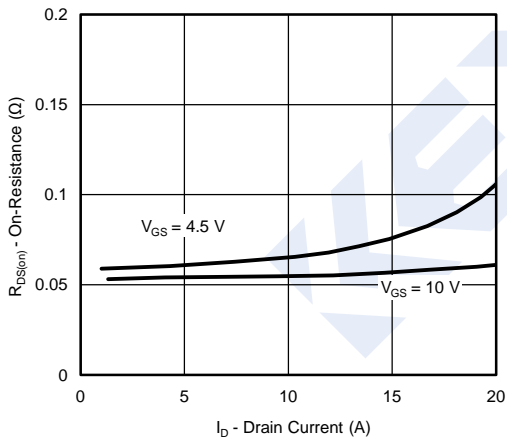
■ Typical Characteristics (25 °C, unless otherwise noted)



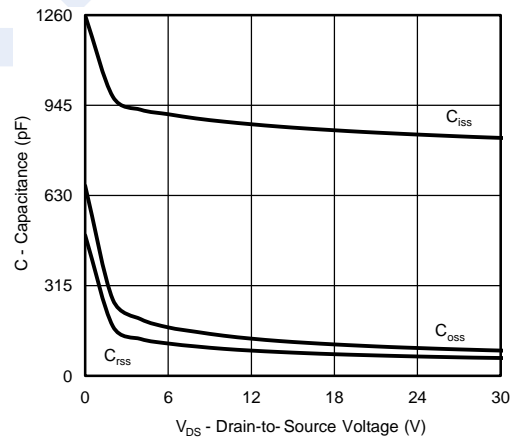
Output Characteristics



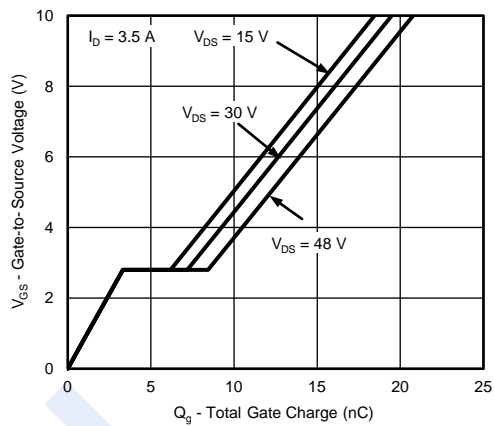
Transfer Characteristics



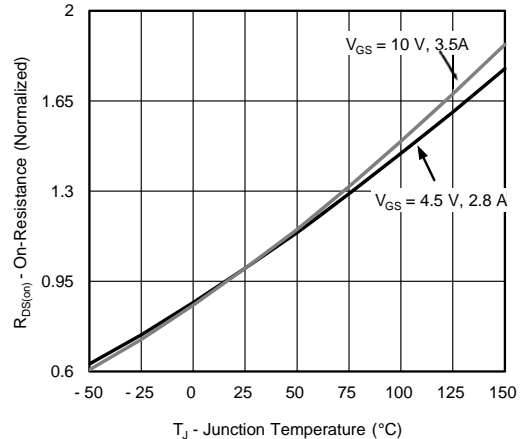
On-Resistance vs. Drain Current



Capacitance



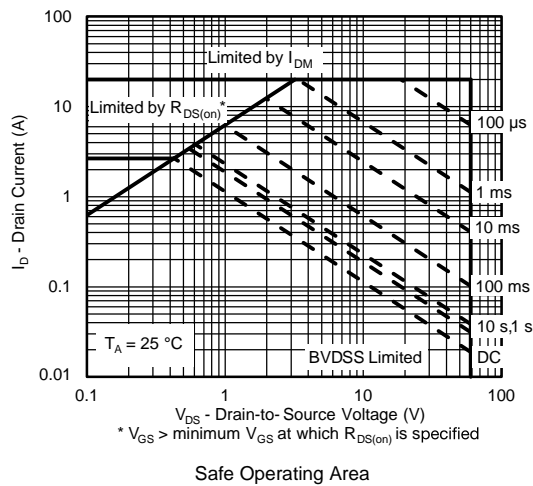
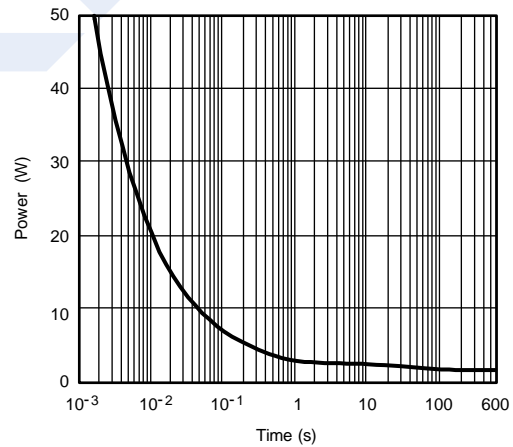
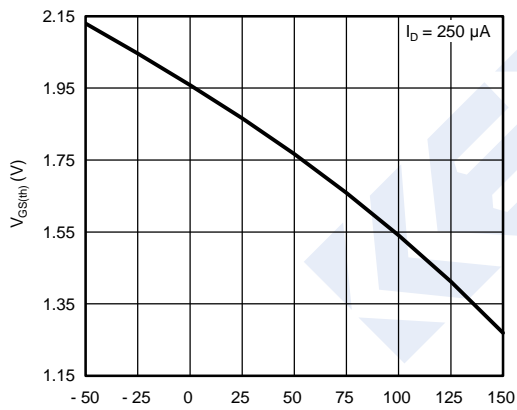
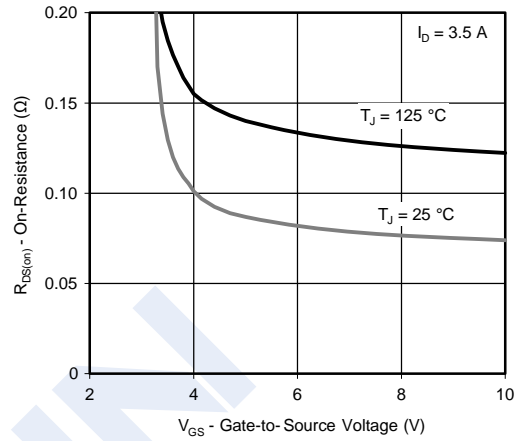
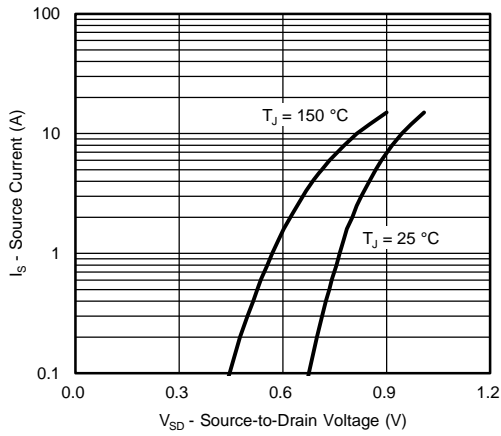
Gate Charge



On-Resistance vs. Junction Temperature

## P-Channel MOSFET 2KJ6068

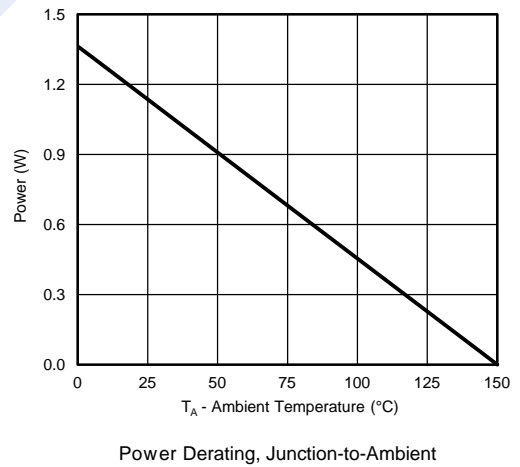
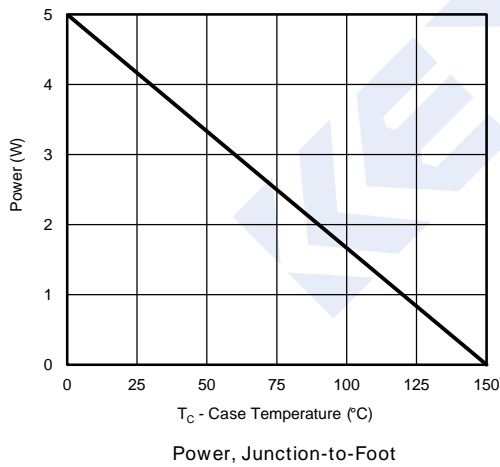
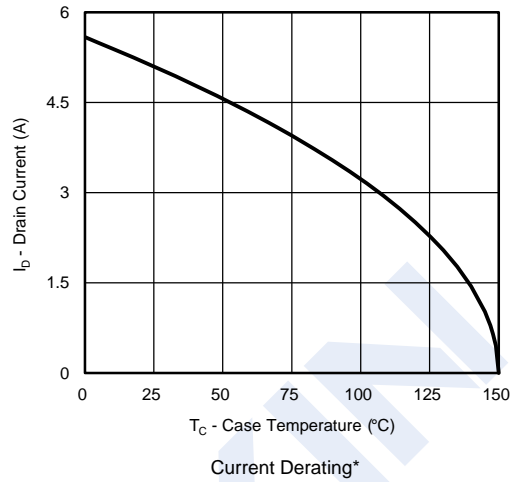
■ Typical Characteristics (25 °C, unless otherwise noted)



## P-Channel MOSFET

### 2KJ6068

#### ■ Typical Characteristics (25 °C, unless otherwise noted)



\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

## P-Channel MOSFET 2KJ6068

■ Typical Characteristics (25 °C, unless otherwise noted)

